

**32V PNP POWER SWITCHING TRANSISTOR IN SOT-89**

**Features**

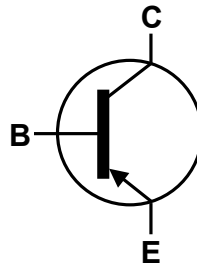
- $BV_{CEO} > -32V$
- $I_C = -1A$  high Continuous Collector Current
- Complementary NPN Type: 2DD1664
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

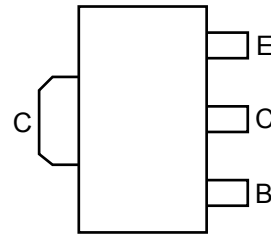
- Case: SOT89
- Case material: molded Plastic. "Green" molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.055 grams (Approximate)



Top View



Device Symbol



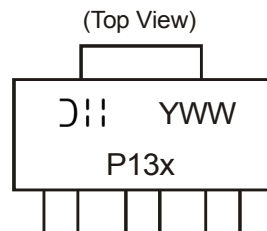
Pin Out  
Top View

**Ordering Information** (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DB1132P-13	P13P	13	12	2,500
2DB1132Q-13	P13Q	13	12	2,500
2DB1132R-13	P13R	13	12	2,500
2DB1132R-13R	P13R	13	12	4,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
  3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

**Marking Information**



P13x = Product Type Marking Code:  
 Where P13P = 2DB1132P  
 P13Q = 2DB1132Q  
 P13R = 2DB1132R  
 YWW = Date Code Marking  
 Y = Last digit of year ex: 7 = 2007  
 WW = Week code 01 - 52

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	$V_{CEO}$	-32	V
Emitter-Base Voltage	$V_{EBO}$	-5	V
Continuous Collector Current	$I_C$	-1	A
Peak Pulse Current	$I_{CM}$	-2	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

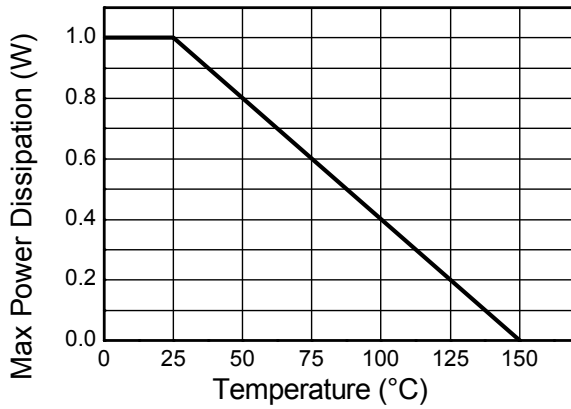
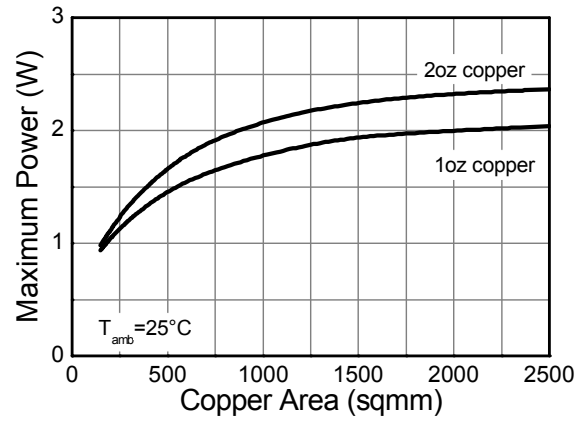
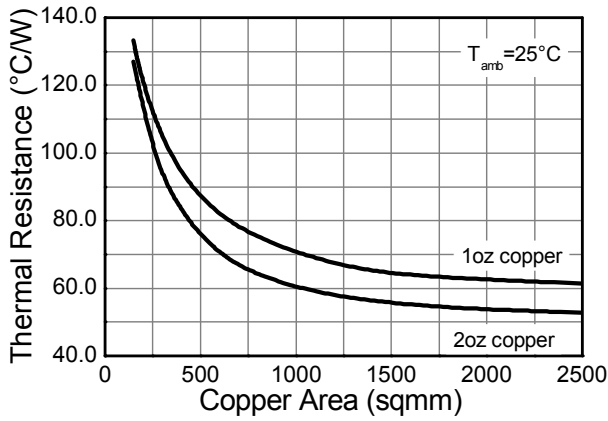
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	(Note 5)	1
		(Note 6)	1.5
		(Note 7)	2.0
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	(Note 5)	125
		(Note 6)	83
		(Note 7)	60
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	22	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 9)

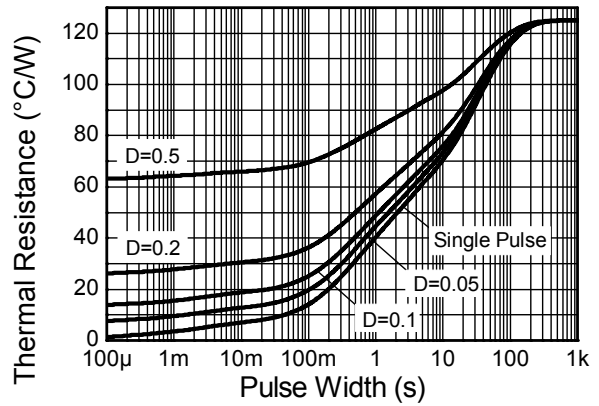
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as note (5), except the device is mounted on 25mm x 25mm 1oz copper.
  7. Same as note (5), except the device is mounted on 50mm x 50mm 1oz copper.
  8. Thermal resistance from junction to solder-point (on the exposed collector pad).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

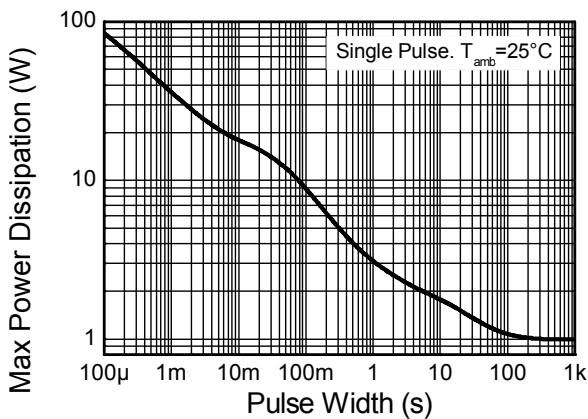
**Thermal Characteristics and Derating Information**



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	-40	—	—	V	$I_C = -50\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 10)	$BV_{CEO}$	-32	—	—	V	$I_C = -1\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-5	—	—	V	$I_E = -50\mu\text{A}$
Collector Cut-off Current	$I_{CBO}$	—	—	-0.5	$\mu\text{A}$	$V_{CB} = -20\text{V}$
Emitter Cut-off Current	$I_{EBO}$	—	—	-0.5	$\mu\text{A}$	$V_{EB} = -4\text{V}$
Static Forward Current Transfer Ratio (Note 10)	2DB1132P	82	—	180	—	$I_C = -100\text{mA}, V_{CE} = -3\text{V}$
	2DB1132Q	120		270		
	2DB1132R	180		390		
Collector-Emitter saturation Voltage (Note 10)	$V_{CE(sat)}$	—	-125	-500	mV	$I_C = -500\text{mA}, I_B = -50\text{mA}$
Transition frequency	$f_T$	—	190	—	MHz	$I_E = 50\text{mA}, V_{CE} = -5\text{V}, f = 30\text{MHz}$
Output Capacitance	$C_{ob}$	—	12	30	pF	$I_E = 0\text{A}, V_{CB} = -10\text{V}, f = 1\text{MHz}$

Notes: 10. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

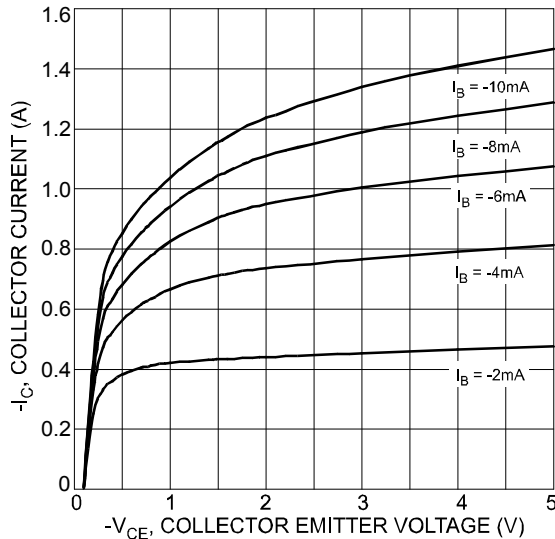


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

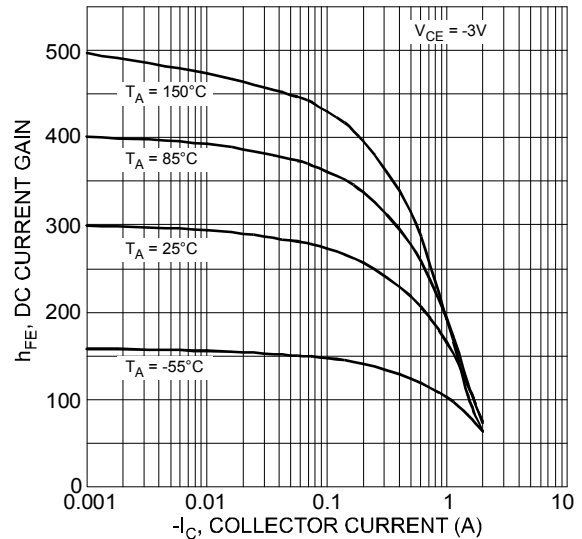


Fig. 3 Typical DC Current Gain vs. Collector Current (2DB1132R)

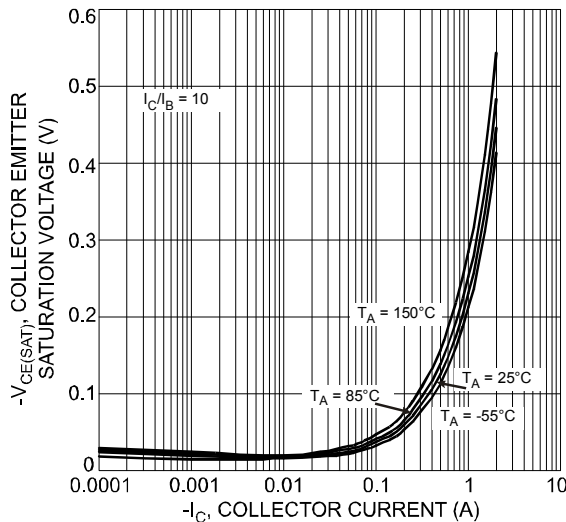


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

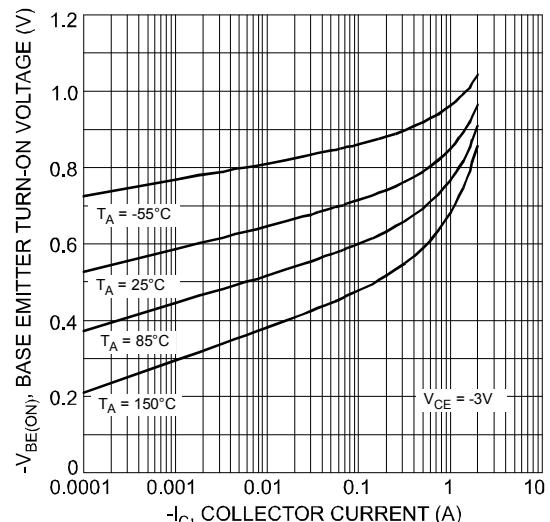


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

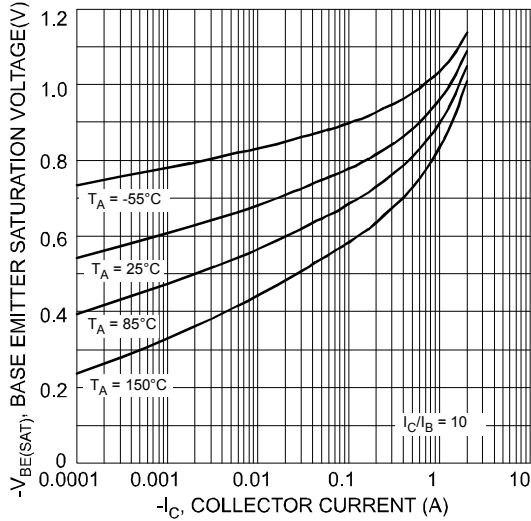


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

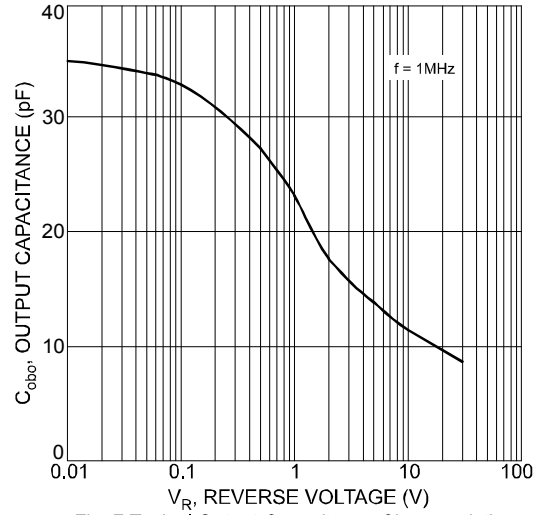


Fig. 7 Typical Output Capacitance Characteristics

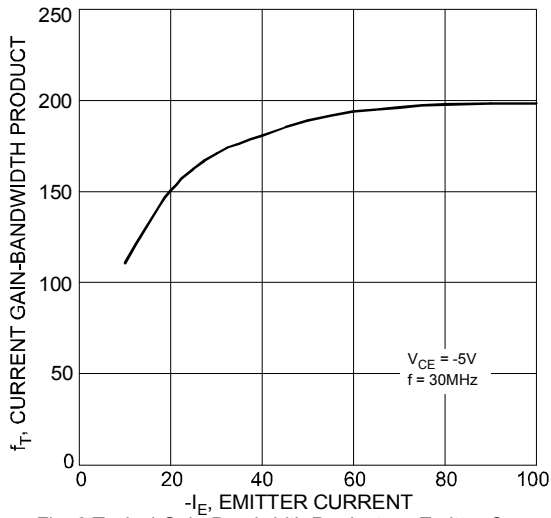
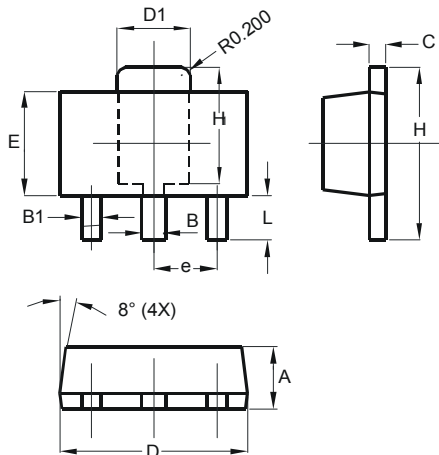


Fig. 8 Typical Gain-Bandwidth Product vs. Emitter Current

## Package Outline Dimensions

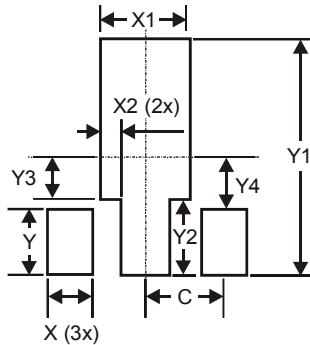
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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